

AMENDMENTS TO THE CLAIMS

Please amend the claims as follows.

1. (Currently Amended) A chip card, comprising:

[-] a card body [(10)], and

[-] chip module [(12)] embedded in said card body and incorporating an integrated circuit, said card body including at least one security feature [(20, 22)] incorporated in a layer, or applied on a surface, of the card body,

wherein said card body comprises an additional tamper-detection layer [(26)] including a conductive pattern [(28)] forming an electrical loop connected between terminals [(34, 36)] of the integrated circuit, said conductive pattern having at least one region [(30, 32)] located beneath or above said security feature [(20, 22)],

and wherein said integrated circuit is adapted to perform an integrity check of said conductive pattern for conditionally performing further operations only in case said integrity is recognized.

2. (Currently Amended) The chip card as in claim 1, wherein said conductive pattern [(28)] has a given impedance or resistance and said integrated circuit is adapted to check whether said impedance or resistance matches a predetermined value stored in a memory of the integrated circuit.

3. (Currently Amended) The chip card as in claim 1, wherein said chip card includes contactless communication features and said conductive pattern [(28)] is part of a tuned circuit co-operating with said integrated circuit for contactless communication.

4. (Currently Amended) The chip card as in claim 1, wherein said at least one security feature [(20, 22)] is a feature from the group including photograph [(20)], hologram, multiple laser image, laser engraving, UV/IR-readable pattern and magnetically-readable encoding.

5. (Original) The chip card as in claim 1, wherein said conductive pattern is made from a conductive ink material.

6. (Original) The chip card as in claim 1, wherein said conductive pattern is made from a transparent or near transparent material.

7. (Currently Amended) The chip card as in claim 1, wherein said conductive pattern ~~[(28)]~~ is connected to said terminals ~~[(34, 36)]~~ of the integrated circuit through permanent bonds.